

Power MOSFET

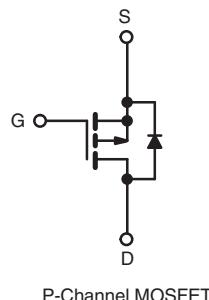
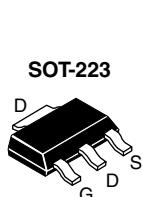
PRODUCT SUMMARY	
V _{DS} (V)	- 100
R _{DS(on)} (Ω)	V _{GS} = - 10 V 1.2
Q _g (Max.) (nC)	8.7
Q _{gs} (nC)	2.2
Q _{gd} (nC)	4.1
Configuration	Single

FEATURES

- Surface Mount
- Available in Tape and Reel
- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- P-Channel
- Fast Switching
- Ease of Parallelizing
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE
Available



DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The SOT-223 package is designed for surface-mount using vapor phase, infrared, or wave soldering techniques. Its unique package design allows for easy automatic pick-and-place as with other SOT or SOIC packages but has the added advantage of improved thermal performance due to an enlarged tab for heatsinking. Power dissipation of greater than 1.25 W is possible in a typical surface mount application.

ORDERING INFORMATION		
Package	SOT-223	SOT-223
Lead (Pb)-free and Halogen-free	SiHFL9110-GE3	SiHFL9110TR-GE3 ^a
Lead (Pb)-free	IRFL9110PbF	IRFL9110TRPbF ^a
	SiHFL9110-E3	SiHFL9110T-E3 ^a

Note

- a. See device orientation.

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V _{DS}	- 100	V
Gate-Source Voltage		V _{GS}	± 20	
Continuous Drain Current	V _{GS} at - 10 V	I _D	- 1.1	A
	T _C = 25 °C		- 0.69	
Pulsed Drain Current ^a		I _{DM}	- 8.8	
Linear Derating Factor			0.025	W/°C
Linear Derating Factor (PCB Mount) ^e			0.017	
Single Pulse Avalanche Energy ^b		E _{AS}	100	mJ
Avalanche Current ^c		I _{AR}	- 1.1	A
Peak Diode Recovery dV/dt ^c		E _{AR}	0.31	mJ
Maximum Power Dissipation	T _C = 25 °C	P _D	3.1	W
Maximum Power Dissipation (PCB Mount) ^e	T _A = 25 °C		2.0	
Peak Diode Recovery dV/dtc		dV/dt	- 5.5	V/ns
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to + 150	°C
Soldering Recommendations (Peak Temperature) ^d	for 10 s		300	

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- V_{DD} = - 25 V, starting T_J = 25 °C, L = 7.7 mH, R_g = 25 Ω, I_{AS} = - 4.4 A (see fig. 12).
- I_{SD} ≤ - 4.4 A, dI/dt ≤ - 75 A/μs, V_{DD} ≤ V_{DS}, T_J ≤ 150 °C.
- 1.6 mm from case.
- When mounted on 1" square PCB (FR-4 or G-10 material).

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient (PCB Mount) ^a	R _{thJA}	-	-	60	°C/W
Maximum Junction-to-Case (Drain)	R _{thJC}	-	-	40	

Note

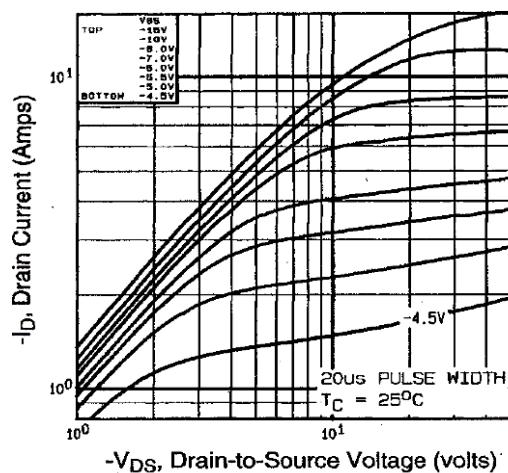
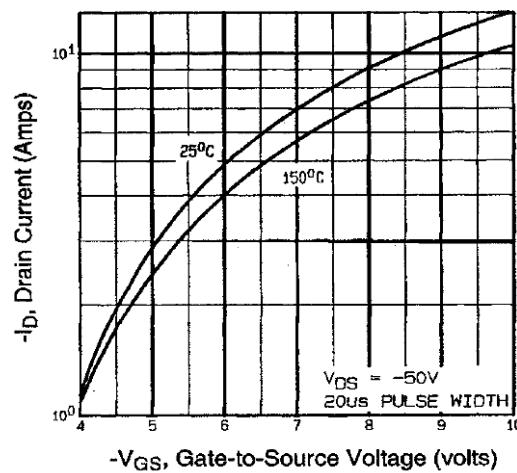
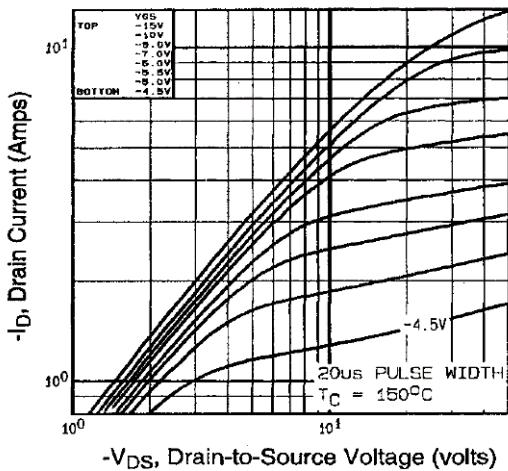
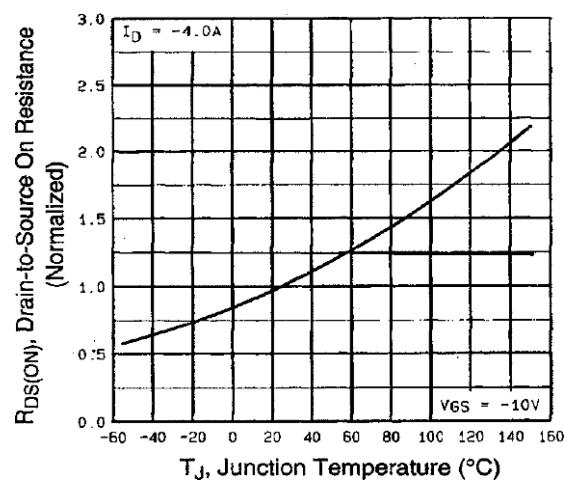
- a. When mounted on 1" square PCB (FR-4 or G-10 material).

SPECIFICATIONS ($T_J = 25^\circ\text{C}$, unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA		- 100	-	-	V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	Reference to 25 °C, I _D = - 1 mA		-	- 0.091	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA		- 2.0	-	- 4.0	V
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DS}	V _{DS} = - 100 V, V _{GS} = 0 V		-	-	- 100	μA
		V _{DS} = - 80 V, V _{GS} = 0 V, T _J = 125 °C		-	-	- 500	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = - 10 V	I _D = - 0.66 A ^b	-	-	1.2	Ω
Forward Transconductance	g _{fs}	V _{DS} = - 50 V, I _D = - 0.66 A		0.82	-	-	S
Dynamic							
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = - 25 V, f = 1.0 MHz, see fig. 5		-	200	-	pF
Output Capacitance	C _{oss}			-	94	-	
Reverse Transfer Capacitance	C _{rss}			-	18	-	
Total Gate Charge	Q _g	V _{GS} = - 10 V	I _D = - 4.0 A, V _{DS} = - 80 V, see fig. 6 and 13 ^b	-	-	8.7	nC
Gate-Source Charge	Q _{gs}			-	-	2.2	
Gate-Drain Charge	Q _{gd}			-	-	4.1	
Turn-On Delay Time	t _{d(on)}			-	10	-	
Rise Time	t _r	V _{DD} = - 50 V, I _D = - 4.0 A, R _G = 24 Ω, R _D = 11 Ω, see fig. 10 ^b		-	27	-	ns
Turn-Off Delay Time	t _{d(off)}		-	15	-		
Fall Time	t _f		-	17	-		
Internal Drain Inductance	L _D		-	4.0	-		
Internal Source Inductance	L _S	Between lead, 6 mm (0.25") from package and center of die contact		-	6.0	-	nH
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p-n junction diode		-	-	- 1.1	A
Pulsed Diode Forward Current ^a	I _{SM}	-		-	- 8.8		
Body Diode Voltage	V _{SD}	T _J = 25 °C, I _S = - 1.1 A, V _{GS} = 0 V ^b		-	-	- 5.5	V
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = - 4.0 A, dI/dt = 100 A/μs ^b		-	80	160	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	0.15	0.30	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L _D)					

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. Pulse width ≤ 300 μs; duty cycle ≤ 2 %.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Fig. 1 - Typical Output Characteristics

Fig. 3 - Typical Transfer Characteristics

Fig. 2 - Typical Output Characteristics

Fig. 4 - Normalized On-Resistance vs. Temperature

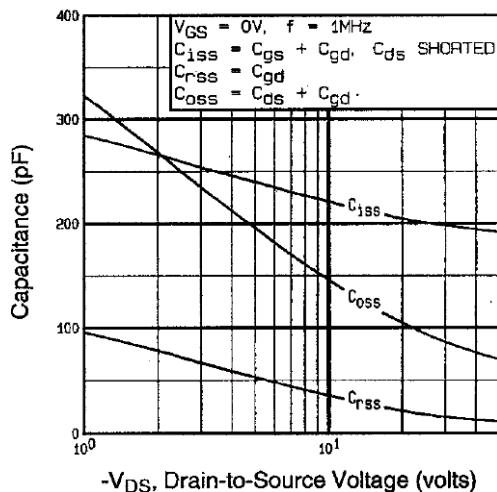


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

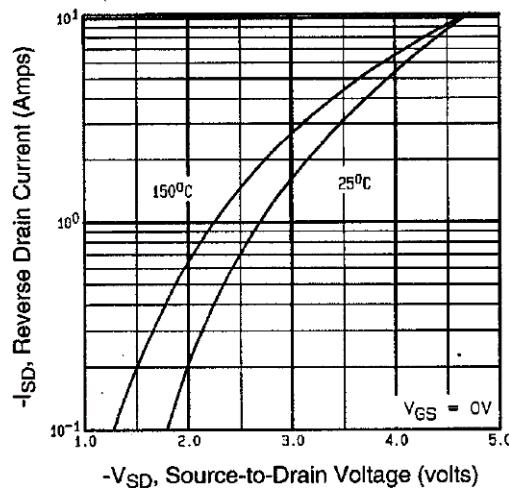


Fig. 7 - Typical Source-Drain Diode Forward Voltage

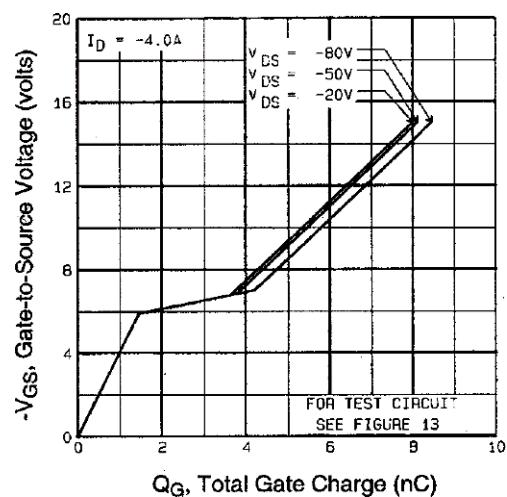


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

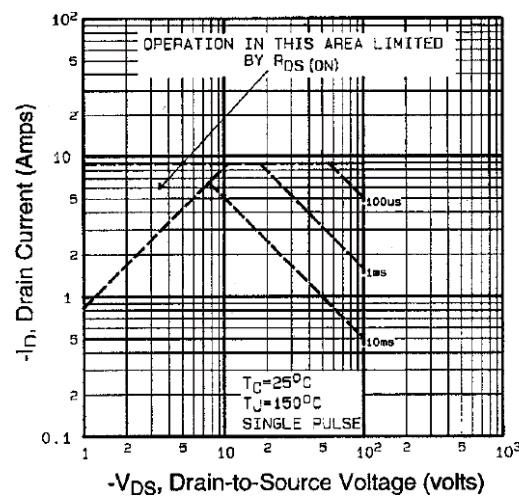


Fig. 8 - Maximum Safe Operating Area

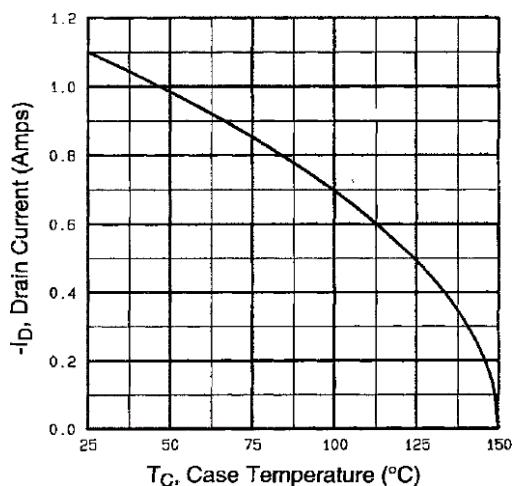


Fig. 9 - Maximum Drain Current vs. Case Temperature

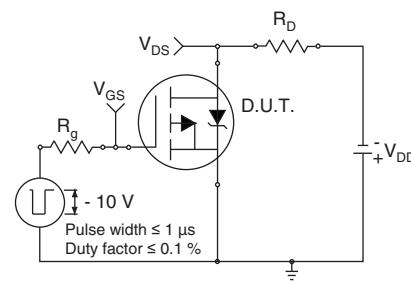


Fig. 10a - Switching Time Test Circuit

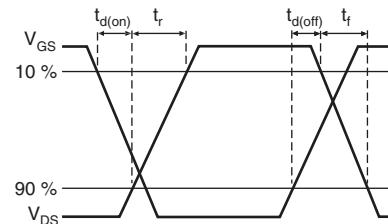


Fig. 10b - Switching Time Waveforms

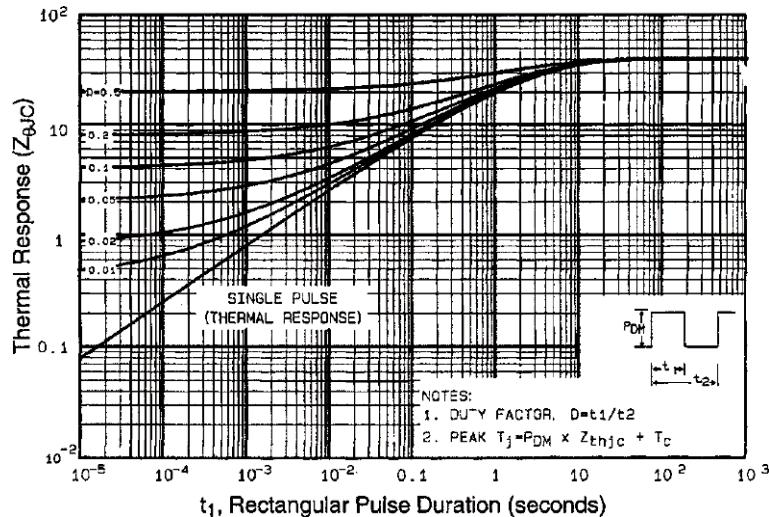


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

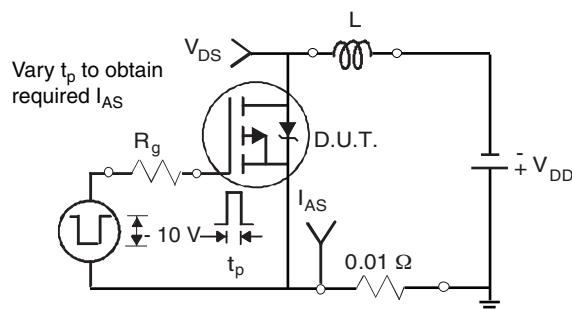


Fig. 12a - Unclamped Inductive Test Circuit

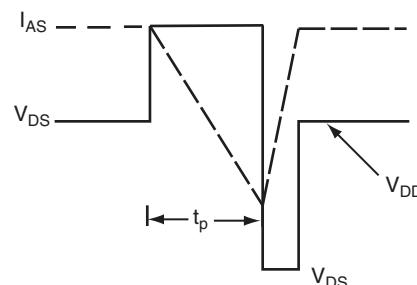


Fig. 12b - Unclamped Inductive Waveforms

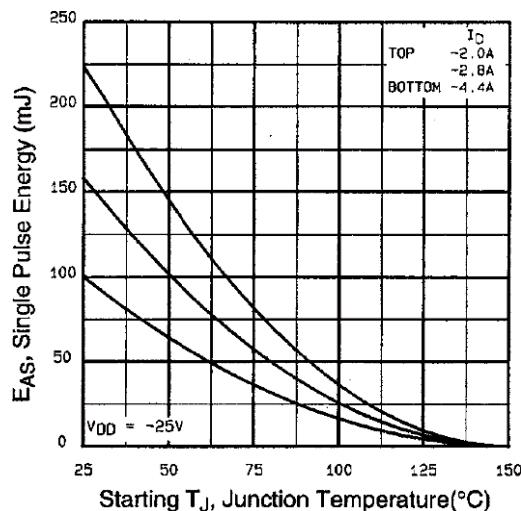


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

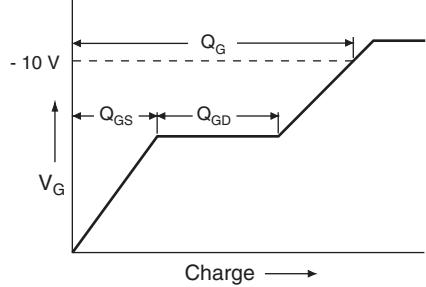


Fig. 13a - Basic Gate Charge Waveform

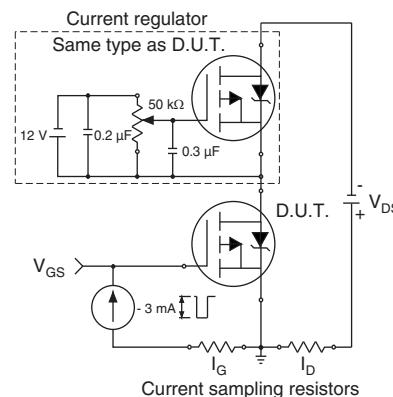
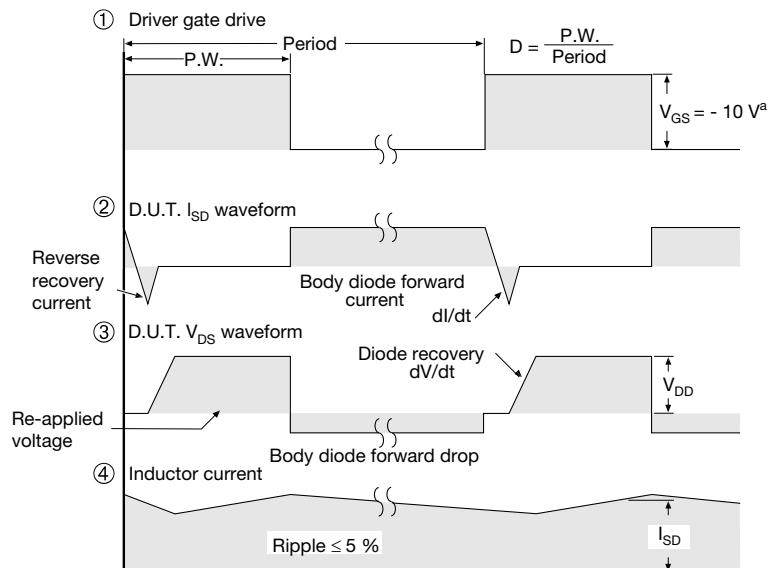
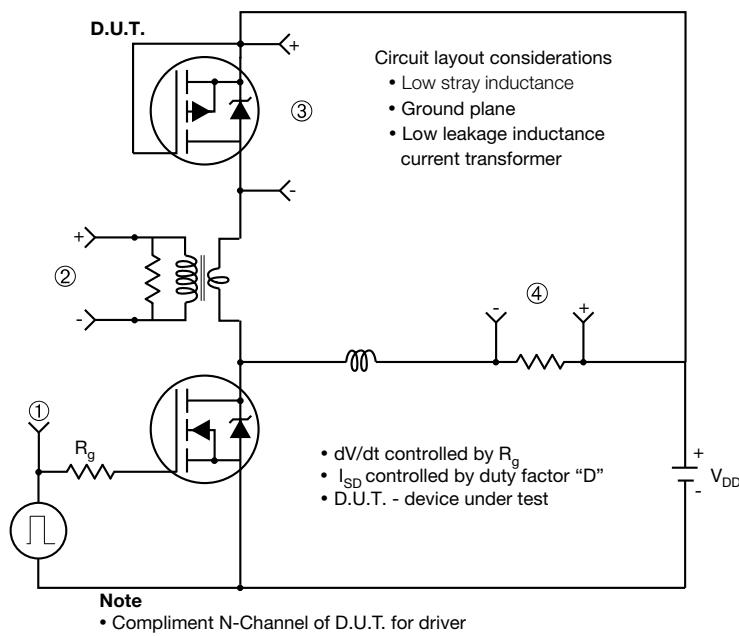
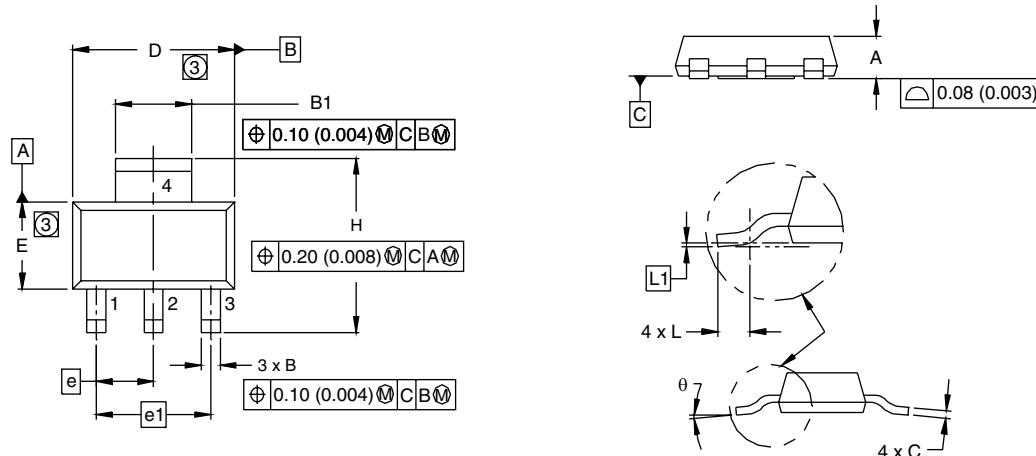


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit

Fig. 14 - For P-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?91196.

SOT-223 (HIGH VOLTAGE)



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	1.55	1.80	0.061	0.071
B	0.65	0.85	0.026	0.033
B1	2.95	3.15	0.116	0.124
C	0.25	0.35	0.010	0.014
D	6.30	6.70	0.248	0.264
E	3.30	3.70	0.130	0.146
e	2.30 BSC		0.0905 BSC	
e1	4.60 BSC		0.181 BSC	
H	6.71	7.29	0.264	0.287
L	0.91	-	0.036	-
L1	0.061 BSC		0.0024 BSC	
θ	-	10°	-	10°
ECN: S-82109-Rev. A, 15-Sep-08				
DWG: 5969				

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension do not include mold flash.
4. Outline conforms to JEDEC outline TO-261AA.



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- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.